



# TJA1057

## High-speed CAN transceiver

Rev. 6 — 24 August 2017

Product data sheet

## 1. General description

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The TJA1057 is part of the Mantis family of high-speed CAN transceivers. It provides an interface between a Controller Area Network (CAN) protocol controller and the physical two-wire CAN bus. The transceiver is designed for high-speed CAN applications in the automotive industry, providing the differential transmit and receive capability to (a microcontroller with) a CAN protocol controller.

The TJA1057 offers a feature set optimized for 12 V automotive applications, with significant improvements over first- and second-generation CAN transceivers from NXP, such as the TJA1050, and excellent ElectroMagnetic Compatibility (EMC) performance. The TJA1057 also displays ideal passive behavior to the CAN bus when the supply voltage is off.

A  $V_{IO}$  pin on the TJA1057GT(K)/3 variants allows for direct interfacing with 3.3 V and 5 V-supplied microcontrollers.

The TJA1057 implements the CAN physical layer as defined in ISO 11898-2:2016 and SAE J2284-1 to SAE J2284-5. The TJA1057T is specified for data rates up to 1 Mbit/s. Additional timing parameters defining loop delay symmetry are specified for the other variants. This implementation enables reliable communication in the CAN FD fast phase at data rates up to 5 Mbit/s.

These features make the TJA1057 an excellent choice for HS-CAN networks that only require basic CAN functionality.

## 2. Features and benefits

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### 2.1 General

- Fully ISO 11898-2:2016 and SAE J2284-1 to SAE J2284-5 compliant
- Optimized for use in 12 V automotive systems
- EMC performance satisfies 'Hardware Requirements for LIN, CAN and FlexRay Interfaces in Automotive Applications', Version 1.3, May 2012.
- $V_{IO}$  input on TJA1057x/3 variants allows for direct interfacing with 3 V to 5 V microcontrollers. Variants without a  $V_{IO}$  pin can interface with 3.3 V and 5 V-supplied microcontrollers, provided the microcontroller I/Os are 5 V tolerant.
- AEC-Q100 qualified
- Dark green product (halogen free and Restriction of Hazardous Substances (RoHS) compliant)
- Both  $V_{IO}$  and non- $V_{IO}$  variants are available in SO8 and leadless HVSON8 (3.0 mm × 3.0 mm) packages; HVSON8 with improved Automated Optical Inspection (AOI) capability.



## 2.2 Predictable and fail-safe behavior

- Functional behavior predictable under all supply conditions
- Transceiver disengages from bus when not powered (zero load)
- Transmit Data (TXD) dominant time-out function
- Internal biasing of TXD and S input pins

## 2.3 Protection

- High ESD handling capability on the bus pins (8 kV IEC and HBM)
- Bus pins protected against transients in automotive environments
- Undervoltage detection on pins  $V_{CC}$  and  $V_{IO}$
- Thermally protected

## 2.4 TJA1057 CAN FD (applicable to all product variants except TJA1057T)

- Timing guaranteed for data rates up to 5 Mbit/s
- Improved TXD to RXD propagation delay of 210 ns

## 3. Quick reference data

Table 1. Quick reference data

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$V_{CC}$	supply voltage		4.75	-	5.25	V
$V_{IO}$	supply voltage on pin $V_{IO}$		2.95	-	5.25	V
$V_{uvd(VCC)}$	undervoltage detection voltage on pin $V_{CC}$		3.5	4	4.3	V
$V_{uvd(VIO)}$	undervoltage detection voltage on pin $V_{IO}$		2.1	-	2.8	V
$I_{CC}$	supply current	Silent mode	0.1	-	1.2	mA
		Normal mode; bus recessive	2	5	10	mA
		Normal mode; bus dominant	20	45	70	mA
$I_{IO}$	supply current on pin $V_{IO}$	Silent mode	-	3	16	$\mu$ A
		Normal mode				
		recessive; $V_{TXD} = V_{IO}$	-	7	30	$\mu$ A
	dominant; $V_{TXD} = 0$ V	-	110	320	$\mu$ A	
$V_{ESD}$	electrostatic discharge voltage	IEC 61000-4-2 at pins CANH and CANL	-8	-	+8	kV
$V_{CANH}$	voltage on pin CANH	limiting value according to IEC60134	-42	-	+42	V
$V_{CANL}$	voltage on pin CANL	limiting value according to IEC60134	-42	-	+42	V
$T_{vj}$	virtual junction temperature		-40	-	+150	$^{\circ}$ C

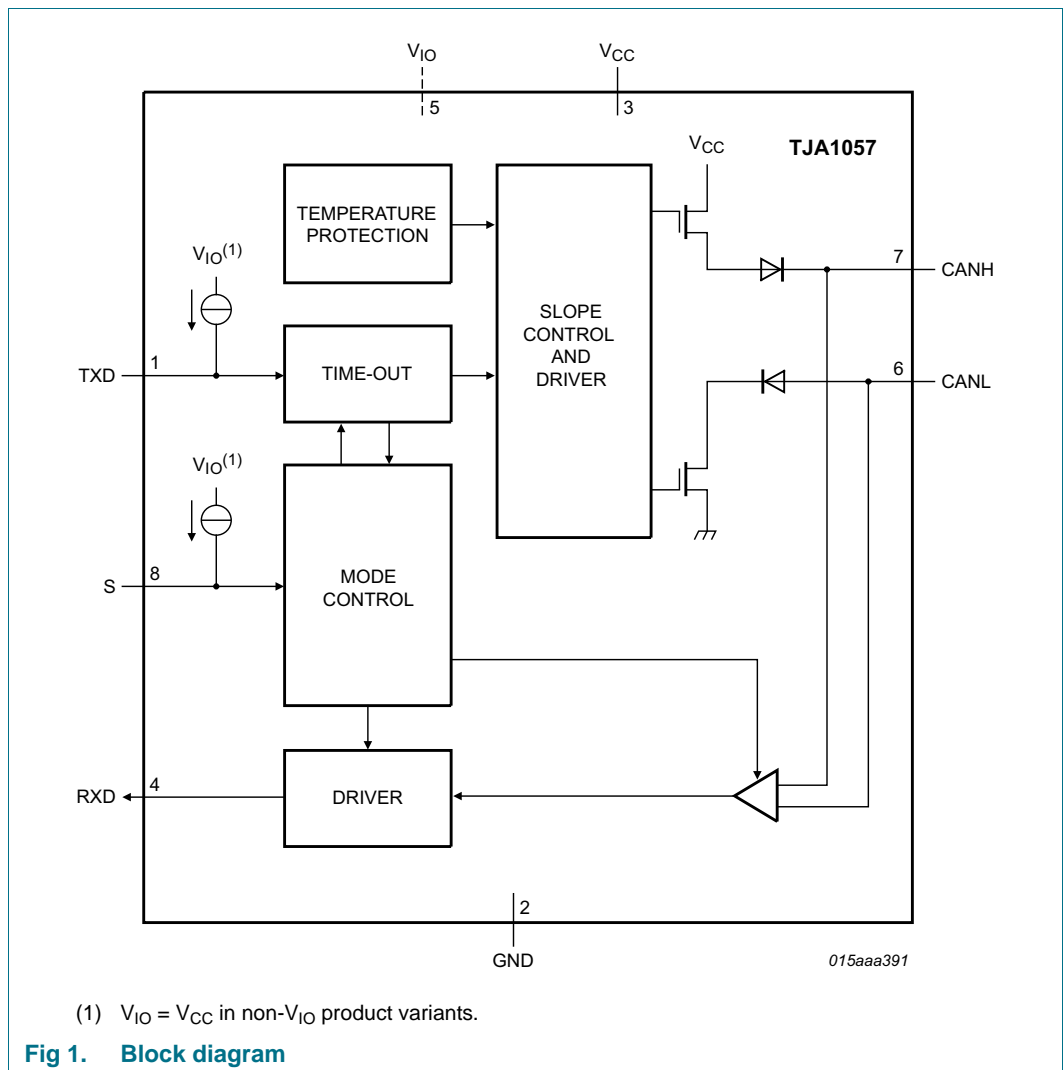
### 4. Ordering information

Table 2. Ordering information

Type number <sup>[1]</sup>	Package		Version
	Name	Description	
TJA1057T TJA1057GT TJA1057GT/3	SO8	plastic small outline package; 8 leads; body width 3.9 mm	SOT96-1
TJA1057GTK TJA1057GTK/3	HVSON8	plastic thermal enhanced very thin small outline package; no leads; 8 terminals; body 3 × 3 × 0.85 mm	SOT782-1

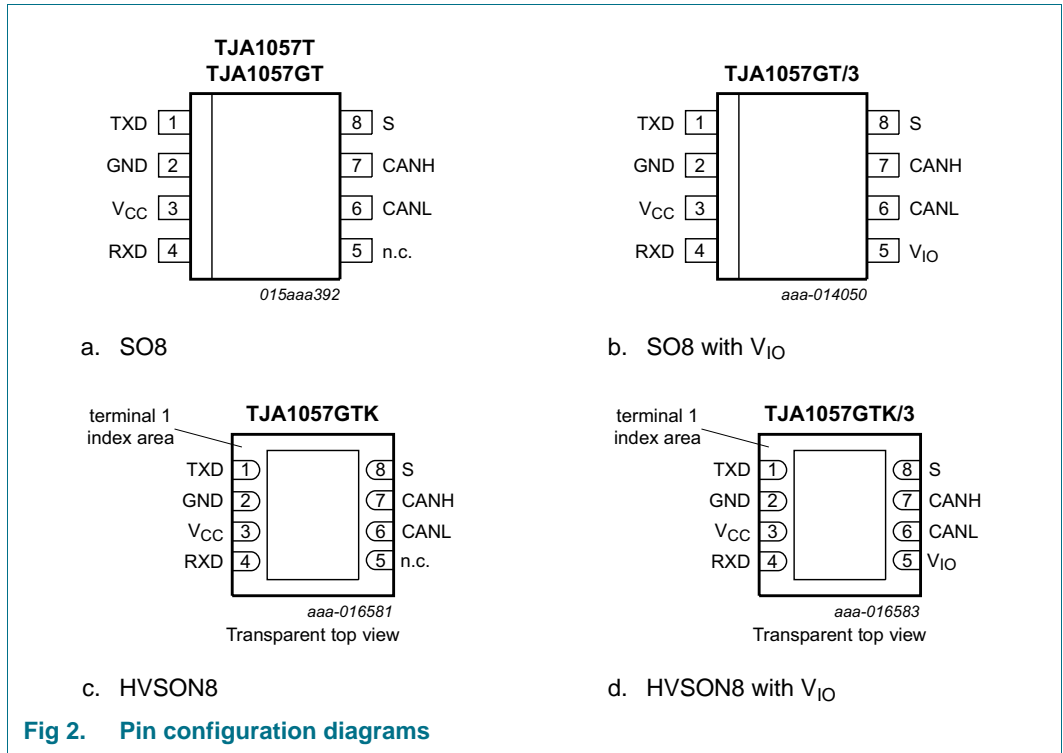
[1] TJA1057GT/3 and TJA1057GTK/3 with V<sub>IO</sub> pin; all variants other than TJA1057T support CAN FD.

### 5. Block diagram



## 6. Pinning information

### 6.1 Pinning



### 6.2 Pin description

Table 3. Pin description

Symbol	Pin	Description
TXD	1	transmit data input
GND <sup>[1]</sup>	2	ground
V <sub>CC</sub>	3	supply voltage
RXD	4	receive data output; reads out data from the bus lines
n.c.	5	not connected in TJA1057T, TJA1057GT and TJA1057GTK
V <sub>IO</sub>	5	supply voltage for I/O level adapter in TJA1057GT/3 and TJA1057GTK/3
CANL	6	LOW-level CAN bus line
CANH	7	HIGH-level CAN bus line
S	8	Silent mode control input

[1] HVSON8 package die supply ground is connected to both the GND pin and the exposed center pad. The GND pin must be soldered to board ground. For enhanced thermal and electrical performance, it is recommended that the exposed center pad also be soldered to board ground.

## 7. Functional description

### 7.1 Operating modes

The TJA1057 supports two operating modes, Normal and Silent. The operating mode is selected via pin S. See [Table 4](#) for a description of the operating modes under normal supply conditions.

**Table 4. Operating modes**

Mode	Inputs		Outputs	
	Pin S	Pin TXD	CAN driver	Pin RXD
Normal	LOW	LOW	dominant	LOW
		HIGH	recessive	LOW when bus dominant
				HIGH when bus recessive
Silent	HIGH	x <sup>[1]</sup>	biased to recessive	LOW when bus dominant
				HIGH when bus recessive

[1] 'x' = don't care.

#### 7.1.1 Normal mode

A LOW level on pin S selects Normal mode. In this mode, the transceiver can transmit and receive data via the bus lines, CANH and CANL (see [Figure 1](#) for the block diagram). The differential receiver converts the analog data on the bus lines into digital data which is output on pin RXD. The slopes of the output signals on the bus lines are controlled internally and are optimized in a way that guarantees the lowest possible EME.

#### 7.1.2 Silent mode

A HIGH level on pin S selects Silent mode. The transmitter is disabled in Silent mode, releasing the bus pins to recessive state. All other IC functions, including the receiver, continue to operate as in Normal mode. Silent mode can be used to prevent a faulty CAN controller disrupting all network communications.

## 7.2 Fail-safe features

### 7.2.1 TXD dominant time-out function

A 'TXD dominant time-out' timer is started when pin TXD is set LOW. If the LOW state on this pin persists for longer than  $t_{to(dom)TXD}$ , the transmitter is disabled, releasing the bus lines to recessive state. This function prevents a hardware and/or software application failure from driving the bus lines to a permanent dominant state (blocking all network communications). The TXD dominant time-out timer is reset when pin TXD is set HIGH. The TXD dominant time-out time also defines the minimum possible bit rate of approximately 25 kbit/s.

### 7.2.2 Internal biasing of TXD and S input pins

Pins TXD and S have internal pull-ups to  $V_{CC}$  (or  $V_{IO}$  in TJA1057GT(K)/3 variants) to ensure a safe, defined state in case one or both of these pins are left floating. Pull-up currents flow in these pins in all states; both pins should be held HIGH in Silent mode to minimize supply current.

### 7.2.3 Undervoltage detection on pins $V_{CC}$ and $V_{IO}$ (TJA1057GT(K)/3)

If  $V_{CC}$  or  $V_{IO}$  drops below the undervoltage detection level,  $V_{uvd(VCC)}/V_{uvd(VIO)}$ , the transceiver switches off and disengages from the bus (zero load; bus pins floating) until the supply voltage has recovered. The output drivers are enabled once both  $V_{CC}$  and  $V_{IO}$  are again within their operating ranges and TXD has been reset to HIGH.

### 7.2.4 Overtemperature protection

The output drivers are protected against overtemperature conditions. If the virtual junction temperature exceeds the shutdown junction temperature,  $T_{j(sd)}$ , both output drivers are disabled. When the virtual junction temperature drops below  $T_{j(sd)}$  again, the output drivers recover once TXD has been reset to HIGH (waiting for TXD to go HIGH prevents output driver oscillation due to small variations in temperature).

### 7.2.5 $V_{IO}$ supply pin (TJA1057x/3 variants)

Pin  $V_{IO}$  should be connected to the microcontroller supply voltage (see [Figure 6](#)). The signal levels on pins TXD, RXD and S will then be adjusted to the I/O levels of the microcontroller, allowing for direct interfacing without additional glue logic.

For versions of the TJA1057 without a  $V_{IO}$  pin, the  $V_{IO}$  input is internally connected to  $V_{CC}$ . The signal levels of pins TXD, RXD and S are set to levels compatible with 5 V microcontrollers.

## 8. Limiting values

**Table 5. Limiting values**

In accordance with the Absolute Maximum Rating System (IEC 60134). All voltages are referenced to GND.

Symbol	Parameter	Conditions	Min	Max	Unit
V <sub>x</sub>	voltage on pin x <sup>[1]</sup>	on pins CANH, CANL	-42	+42	V
		on pins V <sub>CC</sub> , V <sub>IO</sub>	-0.3	+7	V
		on any other pin <sup>[2]</sup>	-0.3	V <sub>IO</sub> <sup>[3]</sup> + 0.3	V
V <sub>(CANH-CANL)</sub>	voltage between pin CANH and pin CANL		-27	+27	V
V <sub>trt</sub>	transient voltage	on pins CANH, CANL <sup>[4]</sup>			
		pulse 1	-100	-	V
		pulse 2a	-	75	V
		pulse 3a	-150	-	V
		pulse 3b	-	100	V
V <sub>ESD</sub>	electrostatic discharge voltage	IEC 61000-4-2 (150 pF, 330 Ω) <sup>[5]</sup>			
		on pins CANH and CANL	-8	+8	kV
		Human Body Model (HBM); 100 pF, 1.5 kΩ <sup>[6]</sup>			
		on pins CANH and CANL	-8	+8	kV
		on any other pin	-4	+4	kV
		Machine Model (MM); 200 pF, 0.75 μH, 10 Ω <sup>[7]</sup>			
		on any pin	-200	+200	V
		Charged Device Model (CDM); field Induced charge; 4 pF <sup>[8]</sup>			
on corner pins	-750	+750	V		
on any other pin	-500	+500	V		
T <sub>vj</sub>	virtual junction temperature	<sup>[9]</sup>	-40	+150	°C
T <sub>stg</sub>	storage temperature		-55	+150	°C

- [1] The device can sustain voltages up to the specified values over the product lifetime, provided applied voltages (including transients) never exceed these values.
- [2] Maximum voltage should never exceed 7 V.
- [3] V<sub>IO</sub> + 0.3 = V<sub>CC</sub> + 0.3 in the non-V<sub>IO</sub> product variants TJA1057(G)T(K).
- [4] According to IEC TS 62228 (2007), Section 4.2.4; parameters for standard pulses defined in ISO7637 part 2: 2004-06.
- [5] According to IEC TS 62228 (2007), Section 4.3; DIN EN 61000-4-2.
- [6] According to AEC-Q100-002.
- [7] According to AEC-Q100-003.
- [8] According to AEC-Q100-011; grade C4B.
- [9] In accordance with IEC 60747-1. An alternative definition of virtual junction temperature is: T<sub>vj</sub> = T<sub>amb</sub> + P × R<sub>th(vj-a)</sub>, where R<sub>th(vj-a)</sub> is a fixed value to be used for the calculation of T<sub>vj</sub>. The rating for T<sub>vj</sub> limits the allowable combinations of power dissipation (P) and ambient temperature (T<sub>amb</sub>).

## 9. Thermal characteristics

**Table 6. Thermal characteristics**

According to IEC 60747-1.

Symbol	Parameter	Conditions	Value	Unit
$R_{th(vj-a)}$	thermal resistance from virtual junction to ambient	SO8 package; in free air	97	K/W
		HVSON8 package; in free air		
		dual-layer board <a href="#">[1]</a>	91	K/W
		four-layer board <a href="#">[2]</a>	52	K/W

- [1] According to JEDEC JESD51-2, JESD51-3 and JESD51-5 at natural convection on 1s board with thermal via array under the exposed pad connected to the second copper layer.
- [2] According to JEDEC JESD51-2, JESD51-5 and JESD51-7 at natural convection on 2s2p board. Board with two inner copper layers (thickness: 35  $\mu\text{m}$ ) and thermal via array under the exposed pad connected to the first inner copper layer.

## 10. Static characteristics

**Table 7. Static characteristics**

$T_{vj} = -40\text{ }^{\circ}\text{C}$  to  $+150\text{ }^{\circ}\text{C}$ ;  $V_{CC} = 4.75\text{ V}$  to  $5.25\text{ V}$ ;  $V_{IO} = 2.95\text{ V}$  to  $5.25\text{ V}$  [\[1\]](#);  $R_L = 60\ \Omega$ ;  $C_L = 100\text{ pF}$  unless specified otherwise; All voltages are defined with respect to ground. Positive currents flow into the IC. [\[2\]](#)

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
<b>Supply; pin <math>V_{CC}</math></b>						
$V_{CC}$	supply voltage		4.75	-	5.25	V
$V_{uvd(VCC)}$	undervoltage detection voltage on pin $V_{CC}$		3.5	4	4.3	V
$I_{CC}$	supply current	Silent mode; $V_{TXD} = V_{IO}$ <a href="#">[3]</a>	0.1	-	1.2	mA
		Normal mode				
		recessive; $V_{TXD} = V_{IO}$ <a href="#">[3]</a>	2	5	10	mA
		dominant; $V_{TXD} = 0\text{ V}$	20	45	70	mA
	dominant; short circuit on bus lines; $V_{TXD} = 0\text{ V}$ ; $-3\text{ V} < (V_{CANH} = V_{CANL}) < +18\text{ V}$	2	80	110	mA	
<b>I/O level adapter supply; pin <math>V_{IO}</math> <a href="#">[1]</a></b>						
$V_{IO}$	supply voltage on pin $V_{IO}$		2.95	-	5.25	V
$V_{uvd(VIO)}$	undervoltage detection voltage on pin $V_{IO}$		2.1	-	2.8	V
$I_{IO}$	supply current on pin $V_{IO}$	Silent mode	-	3	16	$\mu\text{A}$
		Normal mode				
		recessive; $V_{TXD} = V_{IO}$ <a href="#">[3]</a>	-	7	30	$\mu\text{A}$
	dominant; $V_{TXD} = 0\text{ V}$	-	110	320	$\mu\text{A}$	
<b>Silent mode control input; pin S</b>						
$V_{IH}$	HIGH-level input voltage		2	-	$V_{IO}$ <a href="#">[3]</a> + 0.3	V
$V_{IL}$	LOW-level input voltage		-0.3	-	0.8	V
$I_{IH}$	HIGH-level input current	$V_S = V_{IO}$ <a href="#">[3]</a>	-1	-	+1	$\mu\text{A}$
$I_{IL}$	LOW-level input current	$V_S = 0\text{ V}$	-15	-	-1	$\mu\text{A}$



**Table 7. Static characteristics ...continued**

$T_{vj} = -40\text{ }^{\circ}\text{C}$  to  $+150\text{ }^{\circ}\text{C}$ ;  $V_{CC} = 4.75\text{ V}$  to  $5.25\text{ V}$ ;  $V_{IO} = 2.95\text{ V}$  to  $5.25\text{ V}$  [1];  $R_L = 60\ \Omega$ ;  $C_L = 100\text{ pF}$  unless specified otherwise; All voltages are defined with respect to ground. Positive currents flow into the IC. [2]

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
<b>CAN transmit data input; pin TXD</b>						
$V_{IH}$	HIGH-level input voltage		2	-	$V_{IO}$ [3] + 0.3	V
$V_{IL}$	LOW-level input voltage		-0.3	-	0.8	V
$I_{IH}$	HIGH-level input current	$V_{TXD} = V_{IO}$ [3]	-5	-	+5	$\mu\text{A}$
$I_{IL}$	LOW-level input current	$V_{TXD} = 0\text{ V}$	-260	-	-30	$\mu\text{A}$
$C_i$	input capacitance		[4]	5	10	pF
<b>CAN receive data output; pin RXD</b>						
$I_{OH}$	HIGH-level output current	$V_{RXD} = V_{IO}$ [3] - 0.4 V	-8	-3	-1	mA
$I_{OL}$	LOW-level output current	$V_{RXD} = 0.4\text{ V}$ ; bus dominant	1	-	12	mA
<b>Bus lines; pins CANH and CANL</b>						
$V_{O(\text{dom})}$	dominant output voltage	$V_{TXD} = 0\text{ V}$ ; $t < t_{\text{to}(\text{dom})\text{TXD}}$				
		pin CANH; $R_L = 50\ \Omega$ to $65\ \Omega$	2.75	3.5	4.5	V
		pin CANL; $R_L = 50\ \Omega$ to $65\ \Omega$	0.5	1.5	2.25	V
$V_{\text{dom}(\text{TX})\text{sym}}$	transmitter dominant voltage symmetry	$V_{\text{dom}(\text{TX})\text{sym}} = V_{CC} - V_{\text{CANH}} - V_{\text{CANL}}$	-400	-	+400	mV
$V_{\text{TXsym}}$	transmitter voltage symmetry	$V_{\text{TXsym}} = V_{\text{CANH}} + V_{\text{CANL}}$ ; [4] $f_{\text{TXD}} = 250\text{ kHz}$ , $1\text{ MHz}$ and $2.5\text{ MHz}$ ; [5] $C_{\text{SPLIT}} = 4.7\text{ nF}$	$0.9V_{CC}$	-	$1.1V_{CC}$	V
$V_{O(\text{dif})}$	differential output voltage	dominant; $V_{TXD} = 0\text{ V}$ ; $t < t_{\text{to}(\text{dom})\text{TXD}}$				
		$R_L = 50\ \Omega$ to $65\ \Omega$	1.5	-	3	V
		$R_L = 45\ \Omega$ to $70\ \Omega$	1.4	-	3.3	V
		$R_L = 2240\ \Omega$	1.5	-	5	V
		recessive; $V_{TXD} = V_{IO}$ [3]; no load	-50	-	+50	mV
$V_{O(\text{rec})}$	recessive output voltage	$V_{TXD} = V_{IO}$ [3]; no load	2	$0.5V_{CC}$	3	V
$V_{\text{th}(\text{RX})\text{dif}}$	differential receiver threshold voltage	Normal/Silent mode; $-12\text{ V} \leq V_{\text{CANL}} \leq +12\text{ V}$ ; $-12\text{ V} \leq V_{\text{CANH}} \leq +12\text{ V}$	0.5	-	0.9	V
$V_{\text{rec}(\text{RX})}$	receiver recessive voltage	$-12\text{ V} \leq V_{\text{CANL}} \leq +12\text{ V}$ ; $-12\text{ V} \leq V_{\text{CANH}} \leq +12\text{ V}$				
		Normal/Silent mode	-4	-	0.5	V
$V_{\text{dom}(\text{RX})}$	receiver dominant voltage	$-12\text{ V} \leq V_{\text{CANL}} \leq +12\text{ V}$ ; $-12\text{ V} \leq V_{\text{CANH}} \leq +12\text{ V}$				
		Normal/Silent mode	0.9	-	9.0	V
$V_{\text{hys}(\text{RX})\text{dif}}$	differential receiver hysteresis voltage	Normal mode; $-12\text{ V} \leq V_{\text{CANL}} \leq +12\text{ V}$ ; $-12\text{ V} \leq V_{\text{CANH}} \leq +12\text{ V}$	50	-	300	mV
$I_{O(\text{sc})\text{dom}}$	dominant short-circuit output current	$V_{TXD} = 0\text{ V}$ ; $t < t_{\text{to}(\text{dom})\text{TXD}}$ ; $V_{CC} = 5\text{ V}$				
		pin CANH; $V_{\text{CANH}} = -15\text{ V}$ to $+40\text{ V}$	-100	-70	-40	mA
		pin CANL; $V_{\text{CANL}} = -15\text{ V}$ to $+40\text{ V}$	40	70	100	mA
$I_{O(\text{sc})\text{rec}}$	recessive short-circuit output current	Normal mode; $V_{TXD} = V_{CC}$ $V_{\text{CANH}} = V_{\text{CANL}} = -27\text{ V}$ to $+32\text{ V}$	-5	-	+5	mA

**Table 7. Static characteristics ...continued**

$T_{vj} = -40\text{ }^{\circ}\text{C}$  to  $+150\text{ }^{\circ}\text{C}$ ;  $V_{CC} = 4.75\text{ V}$  to  $5.25\text{ V}$ ;  $V_{IO} = 2.95\text{ V}$  to  $5.25\text{ V}$  [1];  $R_L = 60\text{ }\Omega$ ;  $C_L = 100\text{ pF}$  unless specified otherwise; All voltages are defined with respect to ground. Positive currents flow into the IC. [2]

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$I_L$	leakage current	$V_{CC} = 0\text{ V}$ or $V_{CC} = V_{IO} =$ shorted to ground via $47\text{ k}\Omega$ ; $V_{CANH} = V_{CANL} = 5\text{ V}$	-5	-	+5	$\mu\text{A}$
$R_i$	input resistance	$-2\text{ V} \leq V_{CANL} \leq +7\text{ V}$ ; $-2\text{ V} \leq V_{CANH} \leq +7\text{ V}$	[4] 9	15	28	$\text{k}\Omega$
$\Delta R_i$	input resistance deviation	$0\text{ V} \leq V_{CANL} \leq +5\text{ V}$ ; $0\text{ V} \leq V_{CANH} \leq +5\text{ V}$	[4] -3	-	+3	%
$R_{i(\text{dif})}$	differential input resistance	$-2\text{ V} \leq V_{CANL} \leq +7\text{ V}$ ; $-2\text{ V} \leq V_{CANH} \leq +7\text{ V}$	[4] 19	30	52	$\text{k}\Omega$
$C_{i(\text{cm})}$	common-mode input capacitance		[4] -	-	20	$\text{pF}$
$C_{i(\text{dif})}$	differential input capacitance		[4] -	-	10	$\text{pF}$
<b>Temperature detection</b>						
$T_{j(\text{sd})}$	shutdown junction temperature		[4] -	185	-	$^{\circ}\text{C}$

- [1] Only TJA1057GT/3 and TJA1057GTK/3 have a  $V_{IO}$  pin; the  $V_{IO}$  input is internally connected to  $V_{CC}$  in the other variants.
- [2] Factory testing uses correlated test conditions to cover the specified temperature and power supply voltage range.
- [3]  $V_{IO} = V_{CC}$  in non- $V_{IO}$  product variants TJA1057(G)T(K).
- [4] Not tested in production; guaranteed by design.
- [5] The test circuit used to measure the bus output voltage symmetry (which includes  $C_{\text{SPLIT}}$ ) is shown in [Figure 8](#).

## 11. Dynamic characteristics

**Table 8. Dynamic characteristics**

$T_{vj} = -40\text{ }^{\circ}\text{C}$  to  $+150\text{ }^{\circ}\text{C}$ ;  $V_{CC} = 4.75\text{ V}$  to  $5.25\text{ V}$ ;  $V_{IO} = 2.95\text{ V}$  to  $5.25\text{ V}$  [1];  $R_L = 60\text{ }\Omega$ ;  $C_L = 100\text{ pF}$  unless specified otherwise. All voltages are defined with respect to ground. [2]

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
<b>Transceiver timing; pins CANH, CANL, TXD and RXD; see Figure 7 and Figure 3</b>						
$t_{d(\text{TXD-busdom})}$	delay time from TXD to bus dominant	Normal mode	-	65	-	ns
$t_{d(\text{TXD-busrec})}$	delay time from TXD to bus recessive	Normal mode	-	90	-	ns
$t_{d(\text{busdom-RXD})}$	delay time from bus dominant to RXD	Normal mode	-	60	-	ns
$t_{d(\text{busrec-RXD})}$	delay time from bus recessive to RXD	Normal mode	-	65	-	ns
$t_{d(\text{TXDL-RXDL})}$	delay time from TXD LOW to RXD LOW	TJA1057T; Normal mode	50	-	230	ns
		TJA1057GT(/3), TJA1057GTK(/3); Normal mode	50	-	210	ns
$t_{d(\text{TXDH-RXDH})}$	delay time from TXD HIGH to RXD HIGH	TJA1057T; Normal mode	50	-	230	ns
		TJA1057GT(/3), TJA1057GTK(/3); Normal mode	50	-	210	ns
$t_{\text{bit}(\text{bus})}$	transmitted recessive bit width	TJA1057GT(/3), TJA1057GTK(/3)				
		$t_{\text{bit}(\text{TXD})} = 500\text{ ns}$ [3]	435	-	530	ns
		$t_{\text{bit}(\text{TXD})} = 200\text{ ns}$ [3]	155	-	210	ns
$t_{\text{bit}(\text{RXD})}$	bit time on pin RXD	TJA1057GT(/3), TJA1057GTK(/3)				
		$t_{\text{bit}(\text{TXD})} = 500\text{ ns}$ [3]	400	-	550	ns
		$t_{\text{bit}(\text{TXD})} = 200\text{ ns}$ [3]	120	-	220	ns
$\Delta t_{\text{rec}}$	receiver timing symmetry	TJA1057GT(/3), TJA1057GTK(/3)				
		$t_{\text{bit}(\text{TXD})} = 500\text{ ns}$	-65	-	+40	ns
		$t_{\text{bit}(\text{TXD})} = 200\text{ ns}$	-45	-	+15	ns
$t_{\text{to}(\text{dom})\text{TXD}}$	TXD dominant time-out time	$V_{\text{TXD}} = 0\text{ V}$ ; Normal mode	0.8	3	6.5	ms

[1] Only TJA1057GT/3 and TJA1057GTK/3 have a  $V_{IO}$  pin; the  $V_{IO}$  input is internally connected to  $V_{CC}$  in the other variants.

[2] Factory testing uses correlated test conditions to cover the specified temperature and power supply voltage range.

[3] See Figure 4.

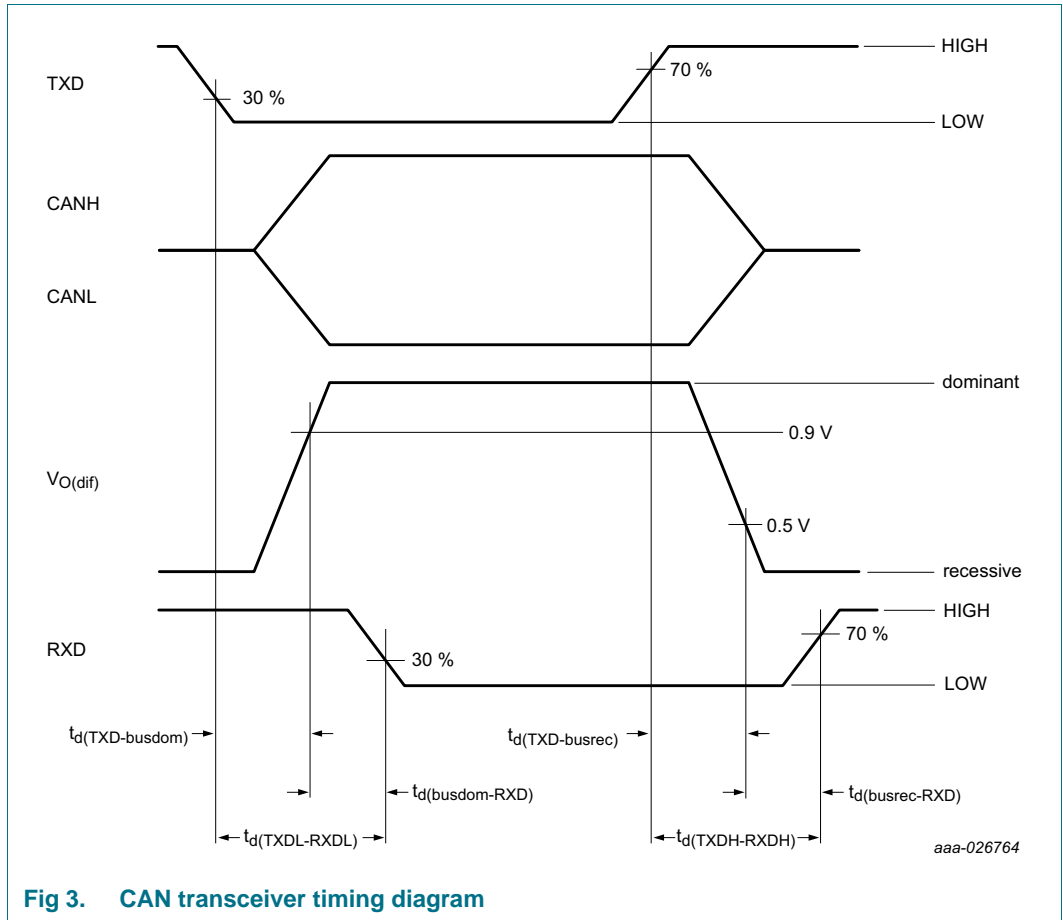


Fig 3. CAN transceiver timing diagram

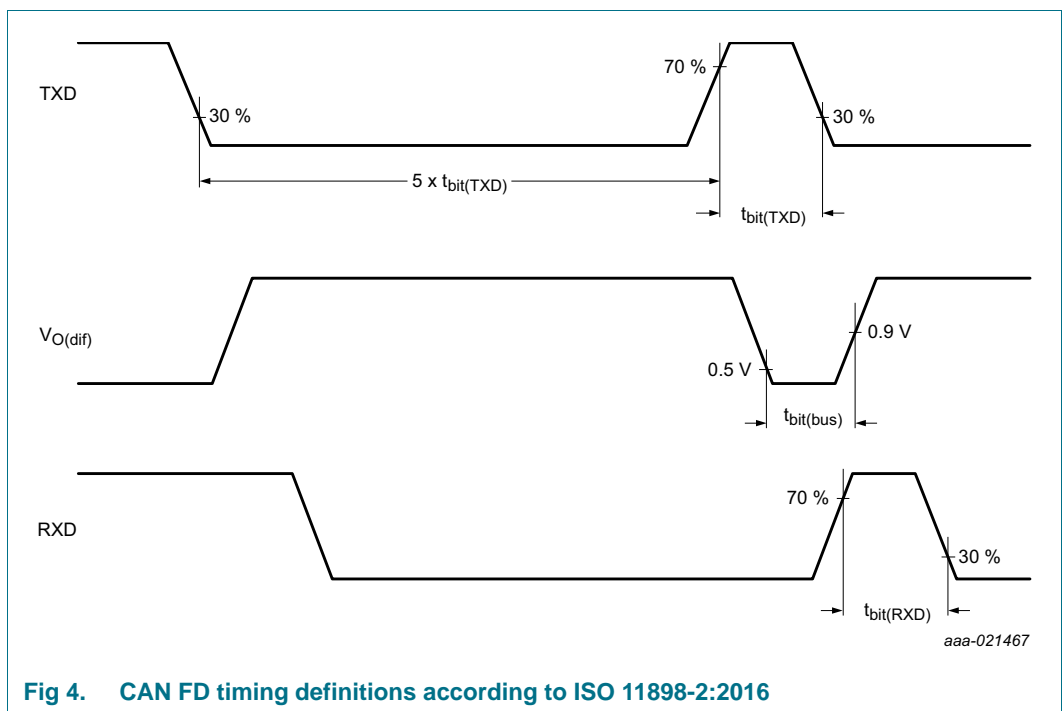
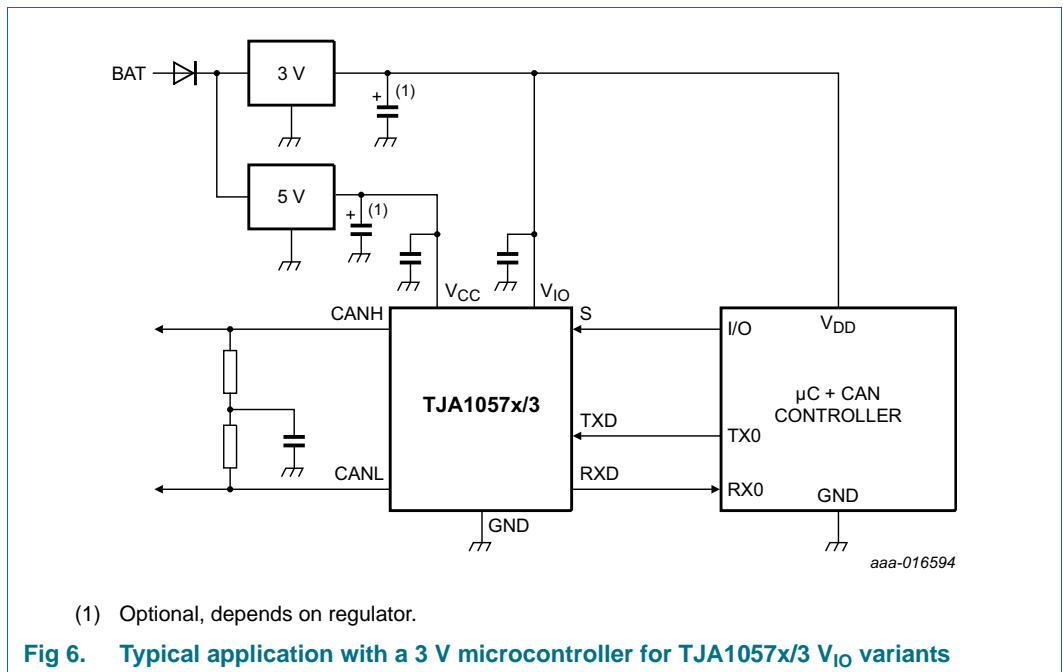
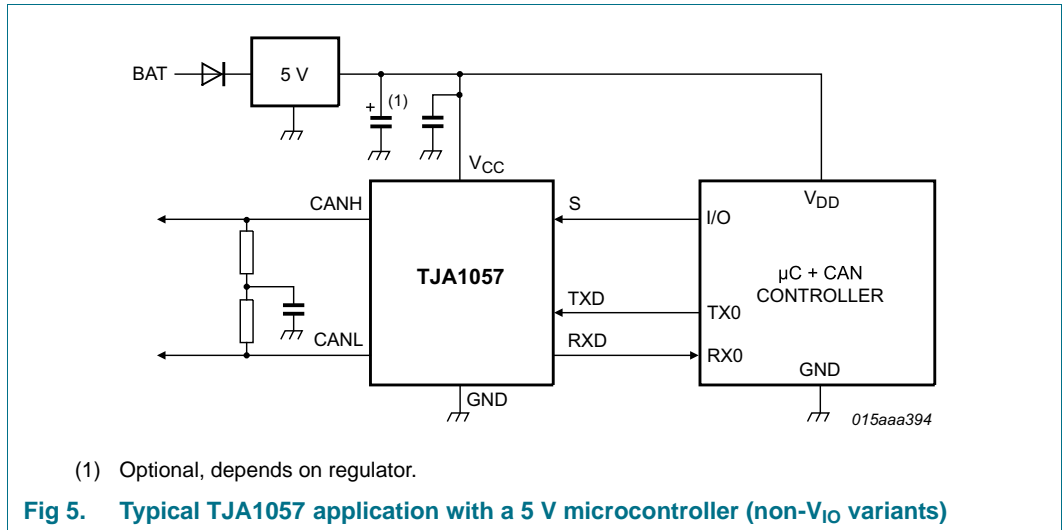


Fig 4. CAN FD timing definitions according to ISO 11898-2:2016

## 12. Application information

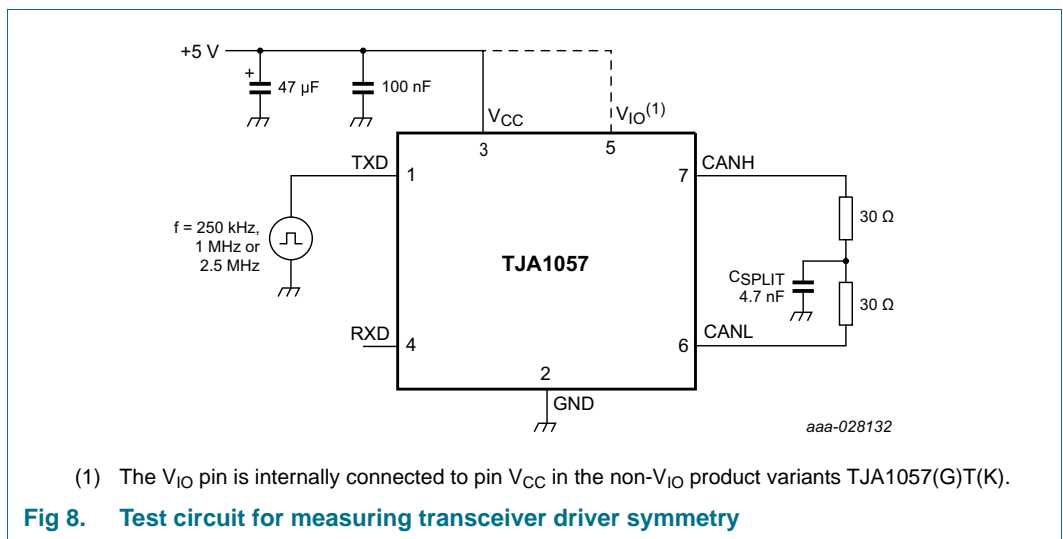
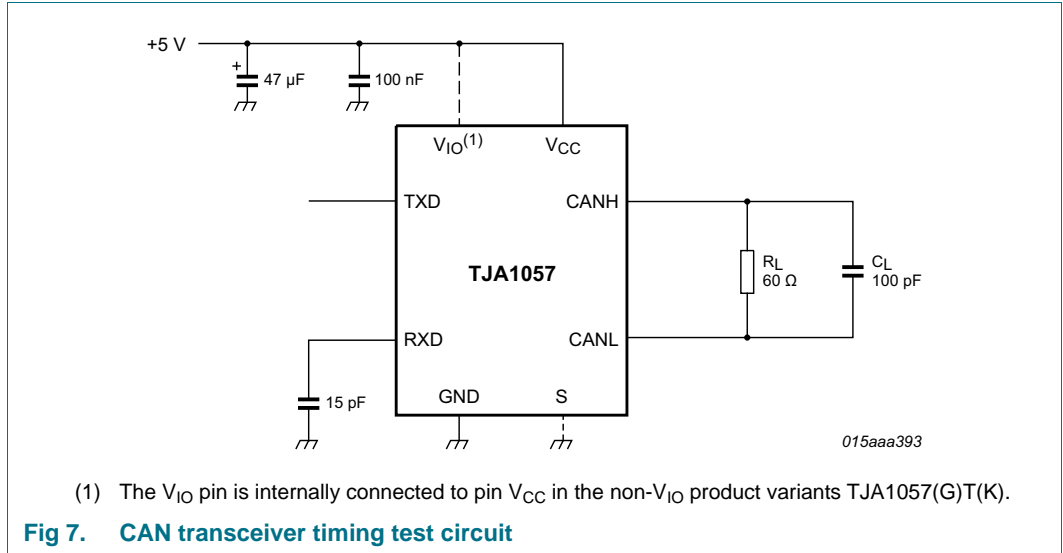
### 12.1 Application diagram



### 12.2 Application hints

Further information on the application of the TJA1057 can be found in NXP application hints *AH1308 Application Hints - Standalone high-speed CAN transceivers Mantis TJA1044/TJA1057 and Dual-Mantis TJA1046*.

13. Test information



13.1 Quality information

This product has been qualified in accordance with the Automotive Electronics Council (AEC) standard Q100 Rev-G - *Failure mechanism based stress test qualification for integrated circuits*, and is suitable for use in automotive applications.

14. Package outline

SO8: plastic small outline package; 8 leads; body width 3.9 mm

SOT96-1



Fig 9. Package outline SOT96-1 (SO8)

HVSON8: plastic thermal enhanced very thin small outline package; no leads;  
8 terminals; body 3 x 3 x 0.85 mm

SOT782-1

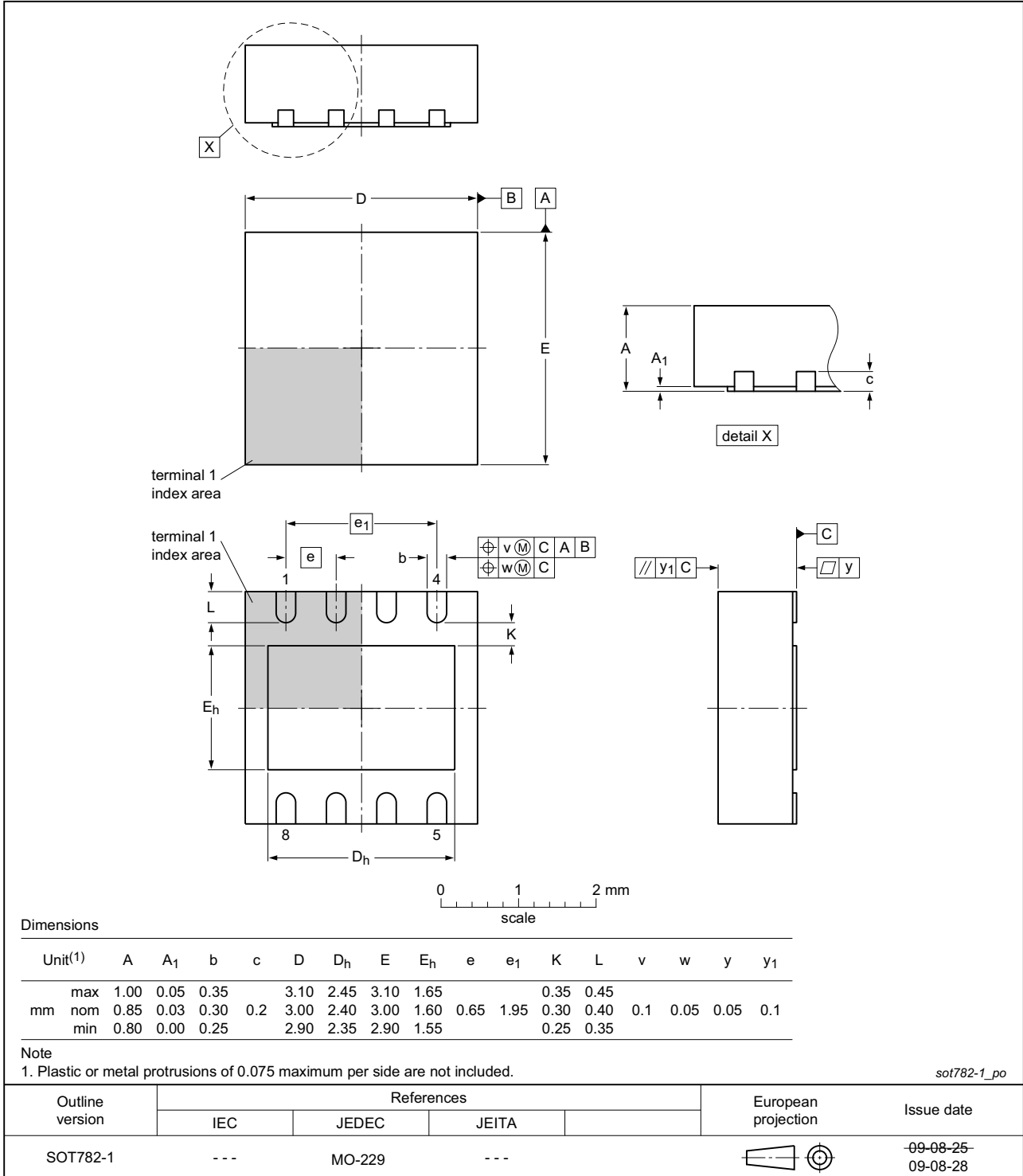


Fig 10. Package outline SOT782-1 (HVSON8)



## 15. Handling information

All input and output pins are protected against ElectroStatic Discharge (ESD) under normal handling. When handling ensure that the appropriate precautions are taken as described in *JESD625-A* or equivalent standards.

## 16. Soldering of SMD packages

This text provides a very brief insight into a complex technology. A more in-depth account of soldering ICs can be found in Application Note *AN10365 "Surface mount reflow soldering description"*.

### 16.1 Introduction to soldering

Soldering is one of the most common methods through which packages are attached to Printed Circuit Boards (PCBs), to form electrical circuits. The soldered joint provides both the mechanical and the electrical connection. There is no single soldering method that is ideal for all IC packages. Wave soldering is often preferred when through-hole and Surface Mount Devices (SMDs) are mixed on one printed wiring board; however, it is not suitable for fine pitch SMDs. Reflow soldering is ideal for the small pitches and high densities that come with increased miniaturization.

### 16.2 Wave and reflow soldering

Wave soldering is a joining technology in which the joints are made by solder coming from a standing wave of liquid solder. The wave soldering process is suitable for the following:

- Through-hole components
- Leaded or leadless SMDs, which are glued to the surface of the printed circuit board

Not all SMDs can be wave soldered. Packages with solder balls, and some leadless packages which have solder lands underneath the body, cannot be wave soldered. Also, leaded SMDs with leads having a pitch smaller than ~0.6 mm cannot be wave soldered, due to an increased probability of bridging.

The reflow soldering process involves applying solder paste to a board, followed by component placement and exposure to a temperature profile. Leaded packages, packages with solder balls, and leadless packages are all reflow solderable.

Key characteristics in both wave and reflow soldering are:

- Board specifications, including the board finish, solder masks and vias
- Package footprints, including solder thieves and orientation
- The moisture sensitivity level of the packages
- Package placement
- Inspection and repair
- Lead-free soldering versus SnPb soldering

### 16.3 Wave soldering

Key characteristics in wave soldering are:

- Process issues, such as application of adhesive and flux, clinching of leads, board transport, the solder wave parameters, and the time during which components are exposed to the wave
- Solder bath specifications, including temperature and impurities

**16.4 Reflow soldering**

Key characteristics in reflow soldering are:

- Lead-free versus SnPb soldering; note that a lead-free reflow process usually leads to higher minimum peak temperatures (see [Figure 11](#)) than a SnPb process, thus reducing the process window
- Solder paste printing issues including smearing, release, and adjusting the process window for a mix of large and small components on one board
- Reflow temperature profile; this profile includes preheat, reflow (in which the board is heated to the peak temperature) and cooling down. It is imperative that the peak temperature is high enough for the solder to make reliable solder joints (a solder paste characteristic). In addition, the peak temperature must be low enough that the packages and/or boards are not damaged. The peak temperature of the package depends on package thickness and volume and is classified in accordance with [Table 9](#) and [10](#)

**Table 9. SnPb eutectic process (from J-STD-020D)**

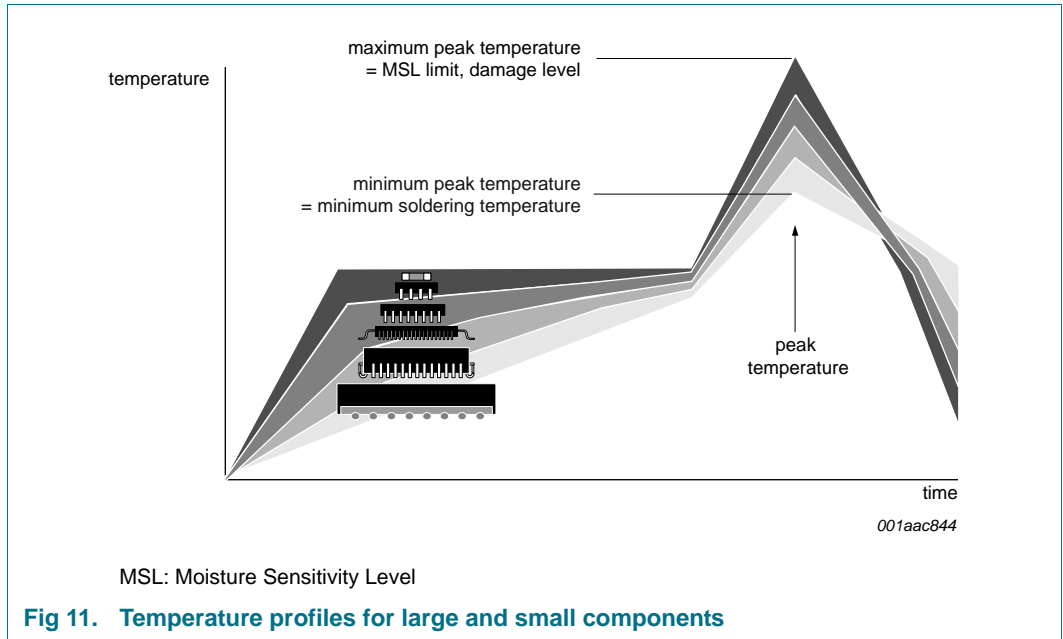
Package thickness (mm)	Package reflow temperature (°C)	
	Volume (mm <sup>3</sup> )	
	< 350	≥ 350
< 2.5	235	220
≥ 2.5	220	220

**Table 10. Lead-free process (from J-STD-020D)**

Package thickness (mm)	Package reflow temperature (°C)		
	Volume (mm <sup>3</sup> )		
	< 350	350 to 2000	> 2000
< 1.6	260	260	260
1.6 to 2.5	260	250	245
> 2.5	250	245	245

Moisture sensitivity precautions, as indicated on the packing, must be respected at all times.

Studies have shown that small packages reach higher temperatures during reflow soldering, see [Figure 11](#).



For further information on temperature profiles, refer to Application Note AN10365 “Surface mount reflow soldering description”.

## 17. Appendix: ISO 11898-2:2016 parameter cross-reference list

Table 11. ISO 11898-2:2016 to NXP data sheet parameter conversion

ISO 11898-2:2016		NXP data sheet	
Parameter	Notation	Symbol	Parameter
<b>HS-PMA dominant output characteristics</b>			
Single ended voltage on CAN_H	$V_{CAN\_H}$	$V_{O(dom)}$	dominant output voltage
Single ended voltage on CAN_L	$V_{CAN\_L}$		
Differential voltage on normal bus load	$V_{Diff}$	$V_{O(dif)}$	differential output voltage
Differential voltage on effective resistance during arbitration			
Optional: Differential voltage on extended bus load range			
<b>HS-PMA driver symmetry</b>			
Driver symmetry	$V_{SYM}$	$V_{TXsym}$	transmitter voltage symmetry
<b>Maximum HS-PMA driver output current</b>			
Absolute current on CAN_H	$I_{CAN\_H}$	$I_{O(sc)dom}$	dominant short-circuit output current
Absolute current on CAN_L	$I_{CAN\_L}$		
<b>HS-PMA recessive output characteristics, bus biasing active/inactive</b>			
Single ended output voltage on CAN_H	$V_{CAN\_H}$	$V_{O(rec)}$	recessive output voltage
Single ended output voltage on CAN_L	$V_{CAN\_L}$		
Differential output voltage	$V_{Diff}$	$V_{O(dif)}$	differential output voltage
<b>Optional HS-PMA transmit dominant timeout</b>			
Transmit dominant timeout, long	$t_{dom}$	$t_{to(dom)TXD}$	TXD dominant time-out time
Transmit dominant timeout, short			
<b>HS-PMA static receiver input characteristics, bus biasing active/inactive</b>			
Recessive state differential input voltage range	$V_{Diff}$	$V_{th(RX)dif}$	differential receiver threshold voltage
Dominant state differential input voltage range		$V_{rec(RX)}$	receiver recessive voltage
		$V_{dom(RX)}$	receiver dominant voltage
<b>HS-PMA receiver input resistance (matching)</b>			
Differential internal resistance	$R_{Diff}$	$R_{i(dif)}$	differential input resistance
Single ended internal resistance	$R_{CAN\_H}$ $R_{CAN\_L}$	$R_i$	input resistance
Matching of internal resistance	MR	$\Delta R_i$	input resistance deviation
<b>HS-PMA implementation loop delay requirement</b>			
Loop delay	$t_{Loop}$	$t_{d(TXDH-RXDH)}$	delay time from TXD HIGH to RXD HIGH
		$t_{d(TXDL-RXDL)}$	delay time from TXD LOW to RXD LOW
<b>Optional HS-PMA implementation data signal timing requirements for use with bit rates above 1 Mbit/s up to 2 Mbit/s and above 2 Mbit/s up to 5 Mbit/s</b>			
Transmitted recessive bit width @ 2 Mbit/s / @ 5 Mbit/s, intended	$t_{Bit(Bus)}$	$t_{bit(bus)}$	transmitted recessive bit width
Received recessive bit width @ 2 Mbit/s / @ 5 Mbit/s	$t_{Bit(RXD)}$	$t_{bit(RXD)}$	bit time on pin RXD
Receiver timing symmetry @ 2 Mbit/s / @ 5 Mbit/s	$\Delta t_{Rec}$	$\Delta t_{rec}$	receiver timing symmetry

Table 11. ISO 11898-2:2016 to NXP data sheet parameter conversion

ISO 11898-2:2016		NXP data sheet	
Parameter	Notation	Symbol	Parameter
<b>HS-PMA maximum ratings of V<sub>CAN_H</sub>, V<sub>CAN_L</sub> and V<sub>Diff</sub></b>			
Maximum rating V <sub>Diff</sub>	V <sub>Diff</sub>	V <sub>(CANH-CANL)</sub>	voltage between pin CANH and pin CANL
General maximum rating V <sub>CAN_H</sub> and V <sub>CAN_L</sub>	V <sub>CAN_H</sub>	V <sub>x</sub>	voltage on pin x
Optional: Extended maximum rating V <sub>CAN_H</sub> and V <sub>CAN_L</sub>	V <sub>CAN_L</sub>		
<b>HS-PMA maximum leakage currents on CAN_H and CAN_L, unpowered</b>			
Leakage current on CAN_H, CAN_L	I <sub>CAN_H</sub> I <sub>CAN_L</sub>	I <sub>L</sub>	leakage current
<b>HS-PMA bus biasing control timings</b>			
CAN activity filter time, long	t <sub>Filter</sub>	t <sub>wake(busdom)</sub> <sup>[1]</sup>	bus dominant wake-up time
CAN activity filter time, short		t <sub>wake(busrec)</sub> <sup>[1]</sup>	bus recessive wake-up time
Wake-up timeout, short	t <sub>Wake</sub>	t <sub>to(wake)bus</sub>	bus wake-up time-out time
Wake-up timeout, long			
Timeout for bus inactivity	t <sub>Silence</sub>	t <sub>to(silence)</sub>	bus silence time-out time
Bus Bias reaction time	t <sub>Bias</sub>	t <sub>d(busact-bias)</sub>	delay time from bus active to bias

[1] t<sub>filtr(wake)bus</sub> - bus wake-up filter time, in devices with basic wake-up functionality

## 18. Revision history

Table 12. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
TJA1057 v.6	20170824	Product data sheet	-	TJA1057 v.5.1
Modifications:	<ul style="list-style-type: none"> <li>• Updated to comply with ISO 11898-2:2016 and SAE J22884-1 through SAE J2284-5 specifications:               <ul style="list-style-type: none"> <li>– <a href="#">Table 7</a>: conditions added to parameters <math>R_i</math>, <math>\Delta R_i</math> and <math>R_{i(dif)}</math>; values/conditions changed for parameters <math>I_{CC}</math>, <math>V_{rec(RX)}</math>, <math>V_{dom(RX)}</math>, <math>I_{O(sc)dom}</math></li> <li>– Additional measurement taken at <math>f_{TXD} = 1</math> MHz and 2.5 MHz for parameter <math>V_{TXsym}</math>; see <a href="#">Table 7</a> “Static characteristics” and <a href="#">Figure 8</a></li> <li>– Thresholds clarified in <a href="#">Figure 3</a></li> </ul> </li> <li>• <a href="#">Section 2.1</a>: text of last entry amended</li> <li>• <a href="#">Table 2</a>: <a href="#">Table note 1</a> amended</li> <li>• <a href="#">Table 5</a>, <a href="#">Table note 2</a> added</li> <li>• Amended <a href="#">Figure 3</a>, <a href="#">Figure 5</a>, <a href="#">Figure 6</a> and <a href="#">Figure 8</a>; figure title changed on <a href="#">Figure 4</a></li> <li>• <a href="#">Section 12.2</a>: reference updated</li> </ul>			
TJA1057 v.5.1	20160523	Product data sheet	-	TJA1057 v.5
TJA1057 v.5	20160128	Product data sheet	-	TJA1057 v.4
TJA1057 v.4	20150710	Product data sheet	-	TJA1057 v.3
TJA1057 v.3	20141119	Product data sheet	-	TJA1057 v.2
TJA1057 v.2	20131030	Product data sheet	-	TJA1057 v.1
TJA1057 v.1	20130530	Preliminary data sheet	-	-

## 19. Legal information

### 19.1 Data sheet status

Document status <sup>[1][2]</sup>	Product status <sup>[3]</sup>	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
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Date of release: 24 August 2017

Document identifier: TJA1057

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- Изготовление тестовой платы монтаж и пусконаладочные работы.



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